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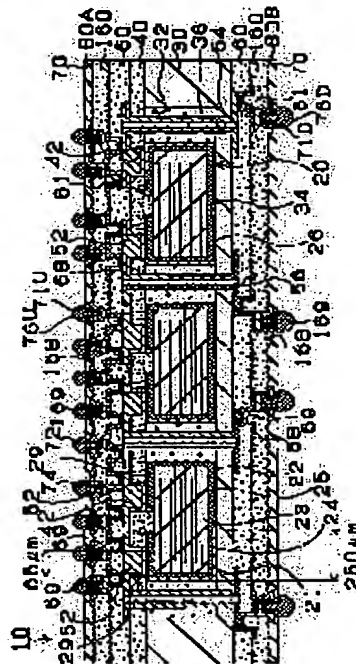
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(54) PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREFOR

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a printed wiring board which has a capacitor inside and has its connection reliability improved, and to provide a manufacturing method for the printed wiring board.

SOLUTION: On a chip capacitor 20 incorporated in a core substrate 30, a relatively large via hole 52 is formed, and in an inter-layer insulating layer 60 on the core substrate 30, via holes 69 connected to the via hole 52 are arranged. Consequently, terminals 21 and 22 of the chip capacitor 20 and the via hole 52 can securely be connected. Further, the surfaces of the metallized terminals 21 and 22 are coated with conductive paste 26, so the surfaces of the terminals 21 and 22 can be flat and the connectivity with the via hole 52 can be increased.



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